

ENGLISH

Datasheet **RS25 Aluminium Housed Resistors**



Product details:

Manufactured in line with the requirements of MIL 18546 and IEC 115, designed for direct heatsink mounting with thermal compound to achieve maximum performance

- High Power to volume
- Wound to maximise High Pulse Capability
- Values from R005 to 100K
- Custom designs welcome
- RoHS Compliant

Heat dissipation:

Whilst the use of proprietary heat sinks with lower thermal resistances is acceptable, uprating is not recommended. For maximum heat transfer it is recommended that a heat sink compound be applied between the resistor base and heat sink chassis mounting surface. It is essential that the maximum hot spot temperature of 200°C is not exceeded, therefore, the resistor must be mounted on a heat sink of correct thermal resistance for the power being dissipated.



Power Overload Pulse Energy RS25 90.0 12 80.0 10 70.0 Pulse Energy (Joules 60.0 Multiple of Rated Power 8 50.0 40.0 6 30.0 4 20.0 10.0 2 0.0 30,000 0.020 1.000 10 100 1,000 10,000 0 1 5 10 20 30 60 120 Resistance (Ohms) Duration of Overload (Secs) Max single pulse (Joules) with > 1 Mins recover Multiple of Rated Power Derating Curve RS25 Surface Temp Rise RS25 120 120 100 100 Surface Temp Rise^oC 80 80 %Full Power 60 60 40 40 20 20 0 0 25 40 60 80 100 120 140 160 180 200 0 5 20 25 1 10 15 Ambient Temperture °C Power Dissipation Watts

Temp. Rise & Power Dissipation



Specifications:

Style MIL-R 18546	RE 70					
Power rating on std. heatsink @25°C	25					
Watts with no heatsink @25°C	9					
Resistance range	R005-36K					
Limiting element voltage	550					
Voltage proof AC Peak	3500					
Voltage proof AC rms.	2500					
Approx weight gms	14					
Typical surface rise HS mounted	4.2					
Standard heatsink	535 cm ²					
	1 mm					

RS10-RS300 Standard:





Dimensions (mm):

Size	A Max	B Max	C Max	D Max	E Max	F <u>+</u> 0.3	G <u>+0.3</u>	H Max	J Max	K Max	L <u>+</u> 0.25
RS25	28.0	51.0	14.8	14.2	27.3	18.3	19.8	7.7	5.2	2.6	3.2